CORNERSTONE

Quick reference design guidelines for the sixteenth fabrication call – October 2019

Sign-up deadline – Friday 15th November 2019

Mask submission deadline – Friday 10th January 2020

File format = *.gdsII*.

Manufacturing grid size = 1 nm.

Design area = **11.47 x 4.9 mm²** or **5.5 x 4.9 mm²**, with 0.5 mm bleed regions on the east and west facets if desired.

Top cell name: 'Cell0_*[Name of Institution]*'.

1. Terms & conditions and cost

All design submissions must agree with the terms and conditions:

www.cornerstone.sotonfab.co.uk/terms-and-conditions

Under no circumstances will we accept designs without agreement with the terms.

Therefore, we strongly recommend that the terms and conditions are pre-authorised by your institution prior to the mask submission date.

A purchase order (PO) must be uploaded at the same time as submitting your mask design in order pay the access fee, detailed in Table 1 below. Purchase orders will not be accepted via email.

Table 1 – Access cost.

Design Area	Access Cost with Heaters*	Access Cost without Heaters
11.47 x 4.9 mm²	£10,000	£5,000
5.5 x 4.9 mm²	£7,000	£3,500

*Quoted prices are exclusive of VAT, import duties, withholding taxes etc.

For information about setting up CORNERSTONE as a supplier to your institution, please contact cornerstone@soton.ac.uk.

Section 7 of the CORNERSTONE 16th Call - Design Rules.pdf document details the design submission process in detail.

2. Design rule changes from previous 340 nm SOI platform call (MPW #12)

The following is a list of design rule changes from the previous 340 nm SOI platform design rules:

1. Tiling will be added by the CORNERSTONE team to the waveguide layer in redundant space on all chips in order to give a consistent etching density and improve etching performance (see Section 8 of the CORNERSTONE 16th Call - Design Rules.pdf document).
2. 2x2 strip MMI for λ = 1.55 µm added.
3. Grating coupler for λ = 1.31 µm added.
4. 1x2 strip MMI for λ = 1.31 µm added.

5. 2x2 strip MMI for λ = 1.31 µm added.
6. Minimum feature size for heater filament layer (GDS layer 39) increased to 2 µm.
7. Standard heater design modified.

3. Design rules summary

A summary of the design rules and GDS layer numbers can be found in Table 2 below.

Table 2 – Design rules summary.

Layer description	GDS number	Field	Min. feature size	Min. gap	Max. feature width	Target critical dimension
Silicon Etch 1 (140 nm ± 10 nm)	6	Dark	200 nm	250 nm	20 µm	265 nm
			200 nm	300 nm	N/a	
Silicon Etch 2 (340 nm to BOX)	3	Light	350 nm	200 nm	N/a	450 nm
	4	Dark	200 nm	350 nm		
Heater Filaments	39	Light	2 µm	10 µm	N/a	2 µm
Heater Contact Pads	41	Light	2 µm	10 µm	N/a	2 µm
Bleed Area	98	N/a	N/a	N/a	N/a	N/a
Cell Outline	99	N/a	N/a	N/a	N/a	N/a
Labels*	100	Dark	250 nm	250 nm	N/a	N/a

*Features drawn in the Labels layer will be merged into Silicon Etch 2 by the CORNERSTONE team.

In order to help you ensure that you comply with the design rules, you can also download a design rule check (DRC) checklist from our website and if you have access to Tanner L-Edit software, a .tdb version of the template containing a DRC file that you can run to automatically find any design rule violations (note that the automatic DRC will not check all of the design rules, so it remains very important to read the design rules in detail).

4. Minimum feature sizes, tolerances and other design rules

- Minimum feature sizes, minimum gaps, and maximum feature widths for each GDS layer are detailed in Table 2.
- The target critical dimension for each GDS layer is listed in Table 2. Note that other feature sizes may have a small dimension bias.
- A minimum spacing between waveguides of at least 5 µm is recommended to avoid power coupling.
- An overlap of at least 200 nm between GDS layers is essential to account for the alignment tolerance between layers.
- All structures drawn in GDS layer 6 (Grating couplers) must overlap by at least 200 nm with GDS layer 3 (Waveguides).
- An overlap of at least 10 µm between GDS layer 39 (Heater Filaments) and GDS layer 41 (Heater Contact Pads) is recommended for optimal heater performance.
- Ensure all structures drawn in GDS layer 6 (Grating couplers) do not overlap with either GDS layer 39 (Heater Filaments) or GDS 41 (Heater Contact Pads).

5. Technical support

For all queries, email cornerstone@soton.ac.uk.